10/600 980

Patent No. 6,891,198

Request for Cert. of Correction dated September 15, 2005

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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:

 $6,891,198 \beta 2$ Confirmation No. 7148

Inventor

:

Matsumura et al.

Issued

Title

:

May 10, 2005

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Film Carrier Tape For

Mounting An Electronic Part

SEP 2 3 2005 of Correction

Certificate

Examiner

:

Long K. Tran

Customer No.

28289

REQUEST FOR CERTIFICATE OF CORRECTION OF PATENT FOR PTO MISTAKE (37 C.F.R. 1.322(a))

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

ATTENTION:

Decision and Certificate of Correction Branch

Patent Issue Division

Sir:

In accordance with 35 U.S.C. §254, we attach hereto Form PTO/SB/44 and a copy of proof of PTO's error and request that a Certificate of Correction be issued in the above-identified patent. The following error appears in the patent as printed:

<u>Face of the Patent</u>, See (57) ABSTRACT, Line 8, "of he undercoating" should read: — of the undercoating —. (See application as filed, page 38, Line 10.)

By

Respectfully submitted,

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Page 1 of 1

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(Also Form PTO-1050)

UNITED STATES PATENT AND TRADEMARK OFFICE CERTIFICATE OF CORRECTION

PATENT NO.

6,891,198 B2

APPLICATION NO.

10/600,980

ISSUE DATE

May 10, 2005

INVENTORS

Matsumura et al.

It is certified that an error appears or errors appear in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

<u>Face of the Patent</u>, See (57) ABSTRACT, Line 8, "of he undercoating" should read: -- of the undercoating --.

MAILING ADDRESS OF SENDER: The Webb Law Firm

700 Koppers Building 436 Seventh Avenue Pittsburgh, PA 15219-1845

This collection of information is required by 37 CFR 1.322, 1.323, and 1.324. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 1.0 hour to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-2450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Attention Certificate of Corrections Branch, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

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FILM CARRIER TAPE FOR MOUNTING ELECTRONIC PART

BACK GROUND OF TWE INVENTION

Field of the Invention

FIELD OF THE INVENTION

PB

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The present invention relates to film carrier tapes for mounting electronic part, which have high reliability in the bonding of electronic parts to be mounted and whose outer connecting terminals, such as solder balls, also have high connection reliability. In the present invention, the film carrier tapes for mounting electronic part include those for TAB (tape automated bonding) method, COF (chip on film) method, CSP (chip size package) method, BGA (ball grid array) method, double-sided metal tape method, multi-layer wiring tape method, wire bonding method and flip chip bonding method.

Description of the Related Art

CEACKGROUND OF THE INVENTION

As methods to mount electronic parts such as IC on film carriers having wiring patterns formed thereon,

20 there are known, for example, TAB (tape automated bonding) method, wire bonding method and flip chip bonding method. As the electronic parts have been more highly integrated and more densely mounted in recent years, film carrier tapes for mounting electronic part

ABSTRACT

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film carrier tape for mounting an electronic part comprising an insulating film and a wiring pattern which is made of a conductive metal and is provided on the surface of the insulating film, wherein an undercoating layer containing nickel as a main constituent is formed on at least a part of the surface of the wiring pattern made of a conductive metal, an intermediate layer containing palladium as a main constituent is formed on the surface of the undercoating layer, a surface layer containing gold as a main constituent is formed on the surface of the intermediate layer, and the average thickness of the intermediate layer containing palladium as a main constituent is not more than 0.04 μ m. According to the present invention, a film carrier tape for mounting electronic part, in which the wire bonding strength to the bonding pad (connecting terminal) and the peel strength of the solder ball to the ball pad are high and the variability range of these strengths is small, is provided.